ABSTRACT OF THE DISCLOSURE

METHOD AND CLEANER COMPOSITION FOR STRIPPING COPPER CONTAINING RESIDUE LAYERS

A cleaner composition for removing from within a microelectronic fabrication a copper containing residue layer in the presence of a copper containing conductor layer, and a method for stripping from within a microelectronic fabrication the copper containing residue layer in the presence of the copper containing conductor layer. The cleaner composition comprises: (1) a hydroxyl amine material; (2) an ammonium fluoride material; and (3) a benzotriazole (BTA) material. The cleaner composition contemplates the method for stripping from within the microelectronic fabrication the copper containing residue layer in the presence of the copper containing conductor layer.

(FIGURE 1 IS SUGGESTED FOR PUBLICATION)